Title (en)

Wiring board

Title (de)

Leiterplatte

Title (fr)

Carte de circuit imprimé

Publication

EP 1130950 B1 20071121 (EN)

Application

EP 01104820 A 20010227

Priority

- JP 2000053997 A 20000229
- JP 2000130989 A 20000428

Abstract (en)

[origin: EP1130950A2] A wiring board (1) of the present invention readily controls a power source voltage and unwanted irradiation noises developed across a power source layer (5) and a ground layer (6) over a broad range of frequencies with a simple arrangement. The wiring board (1) has an on-board surface (3) on the surface of a dielectric substrate (2), on which a semiconductor device (4) or the like is mounted, and a power source layer (5) and a ground layer (6), which are made of a conductor material principally composed of at least one kind of element selected from Cu, W, and Mo, are provided on the back surface of the dielectric substrate (2) or within the same. The periphery of at least one of low resistance areas (5a, 6a) of the power source layer (5) and ground layer (6), respectively is provided with a corresponding high resistance area (5b or 6b) having a higher sheet resistance than that of the respective low resistance areas (5a, 5b). <IMAGE>

IPC 8 full level

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CPC (source: EP US)

H01L 23/50 (2013.01 - EP US); **H05K 1/0216** (2013.01 - EP US); **H05K 1/0234** (2013.01 - EP US); **H05K 1/167** (2013.01 - EP US); H01L 2924/0002 (2013.01 - EP US); H01L 2924/09701 (2013.01 - EP US); H01L 2924/3011 (2013.01 - EP US); H05K 1/0224 (2013.01 - EP US); H05K 1/0298 (2013.01 - EP US); H05K 2201/093 (2013.01 - EP US); H05K 2201/09309 (2013.01 - EP US); H05K 2201/0969 (2013.01 - EP US); H05K 2201/098 (2013.01 - EP US); H05K 2201/10689 (2013.01 - EP US)

Citation (examination)

US 5898576 A 19990427 - LOCKWOOD JOHN J [US], et al

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